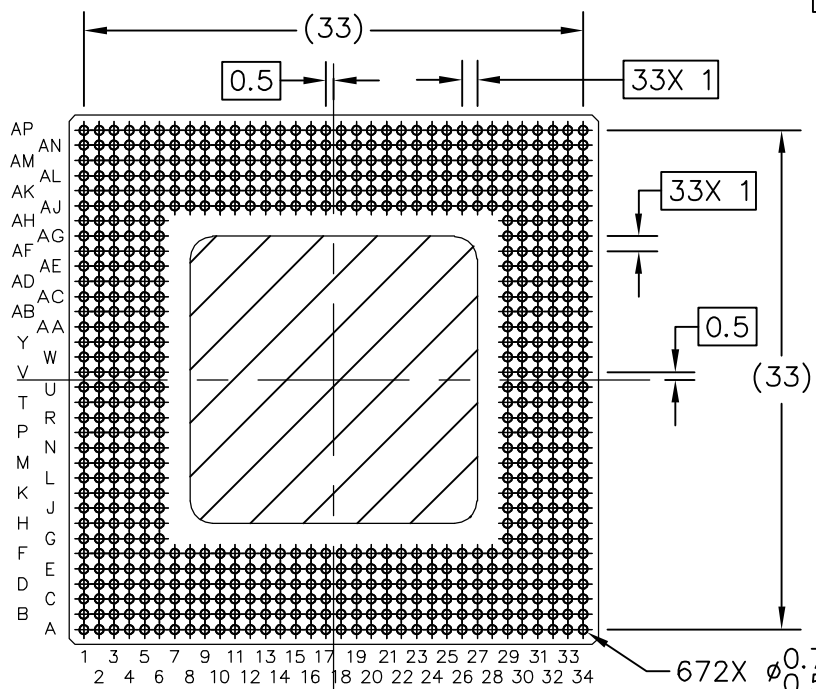
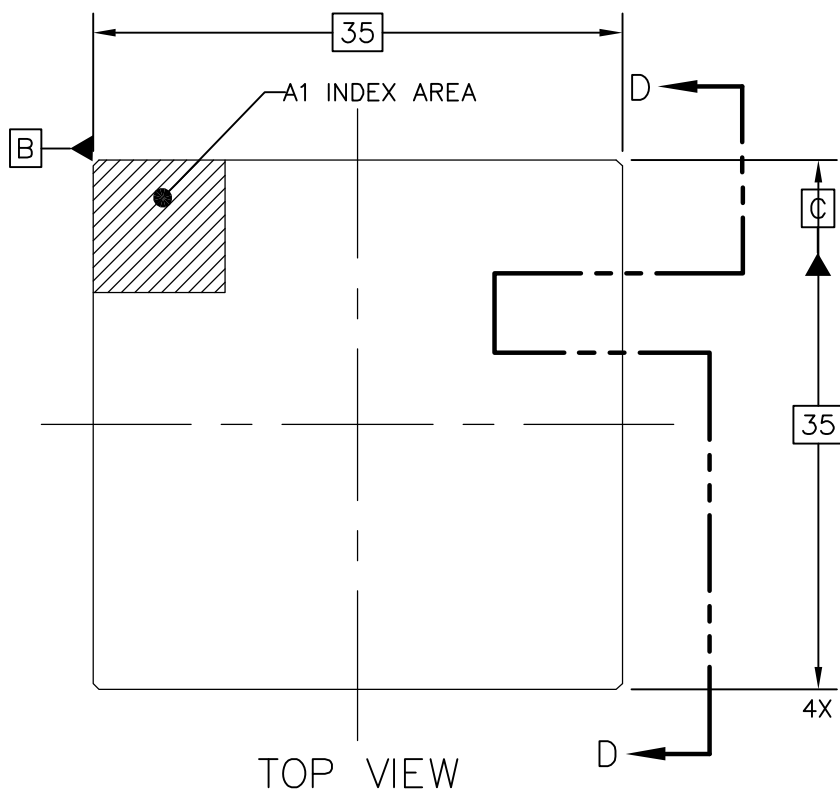
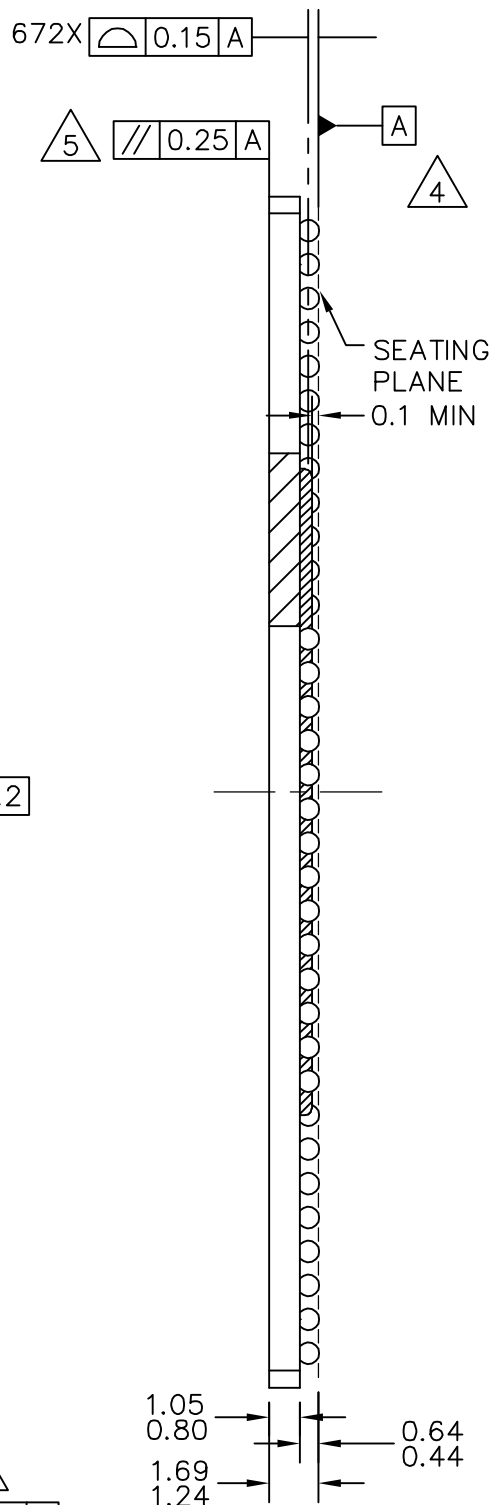
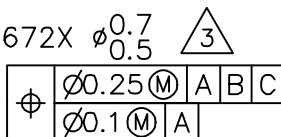




BOTTOM VIEW



SECTION D-D

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MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: 672 I/O TAPE BGA,
35 X 35 PKG,
1 MM PITCH

DOCUMENT NO: 98ARE10569D

REV: A

CASE NUMBER: 1589-02

26 NOV 2008

STANDARD: NON-JEDEC

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: 672 I/O TAPE BGA, 35 X 35 PKG, 1 MM PITCH		DOCUMENT NO: 98ARE10569D		REV: A	
		CASE NUMBER: 1589-02		26 NOV 2008	
		STANDARD: NON-JEDEC			